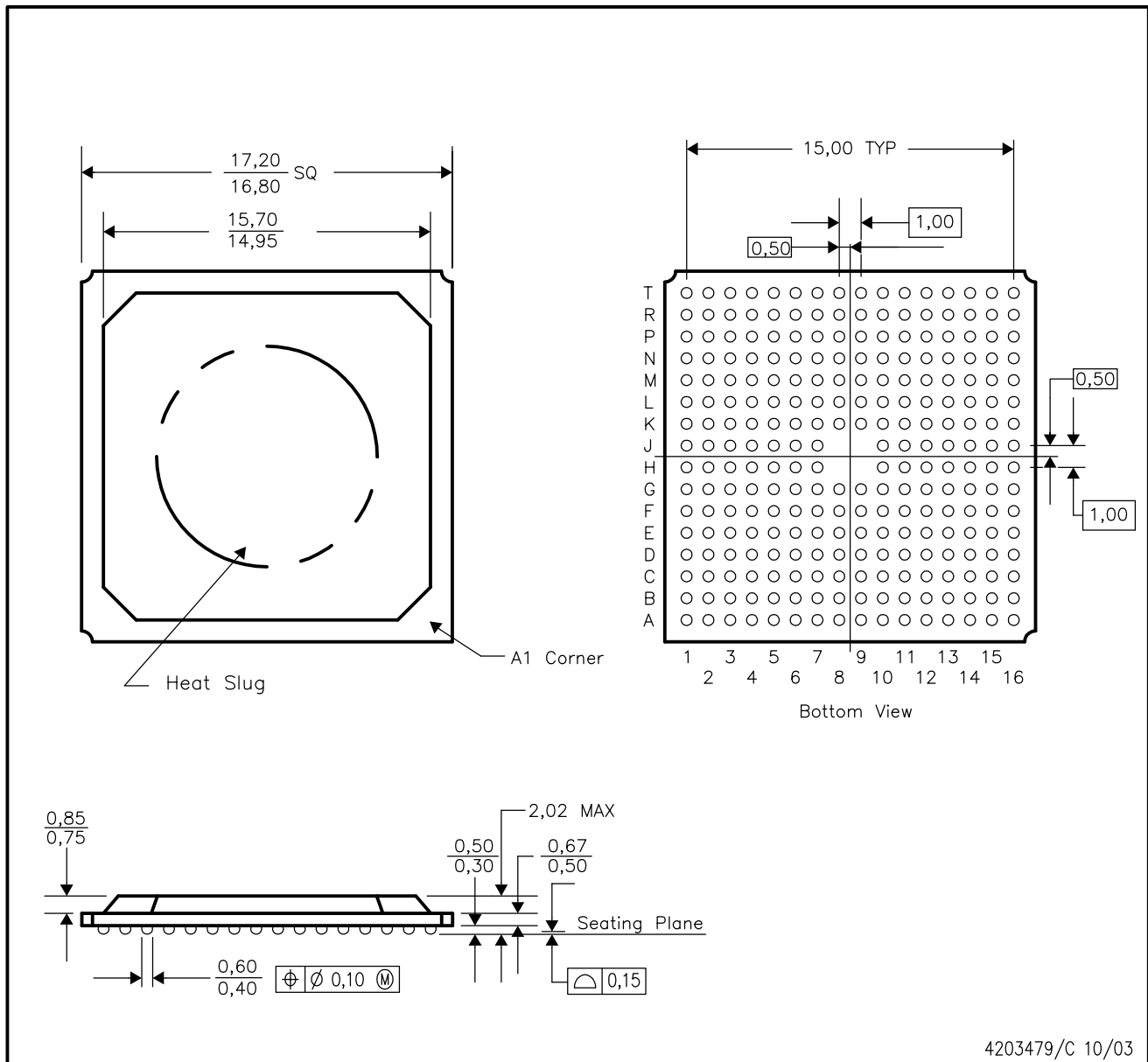


GDJ (S-PBGA-N252)

PLASTIC BALL GRID ARRAY



4203479/C 10/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Thermally enhanced plastic package with heat slug (HSL).

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